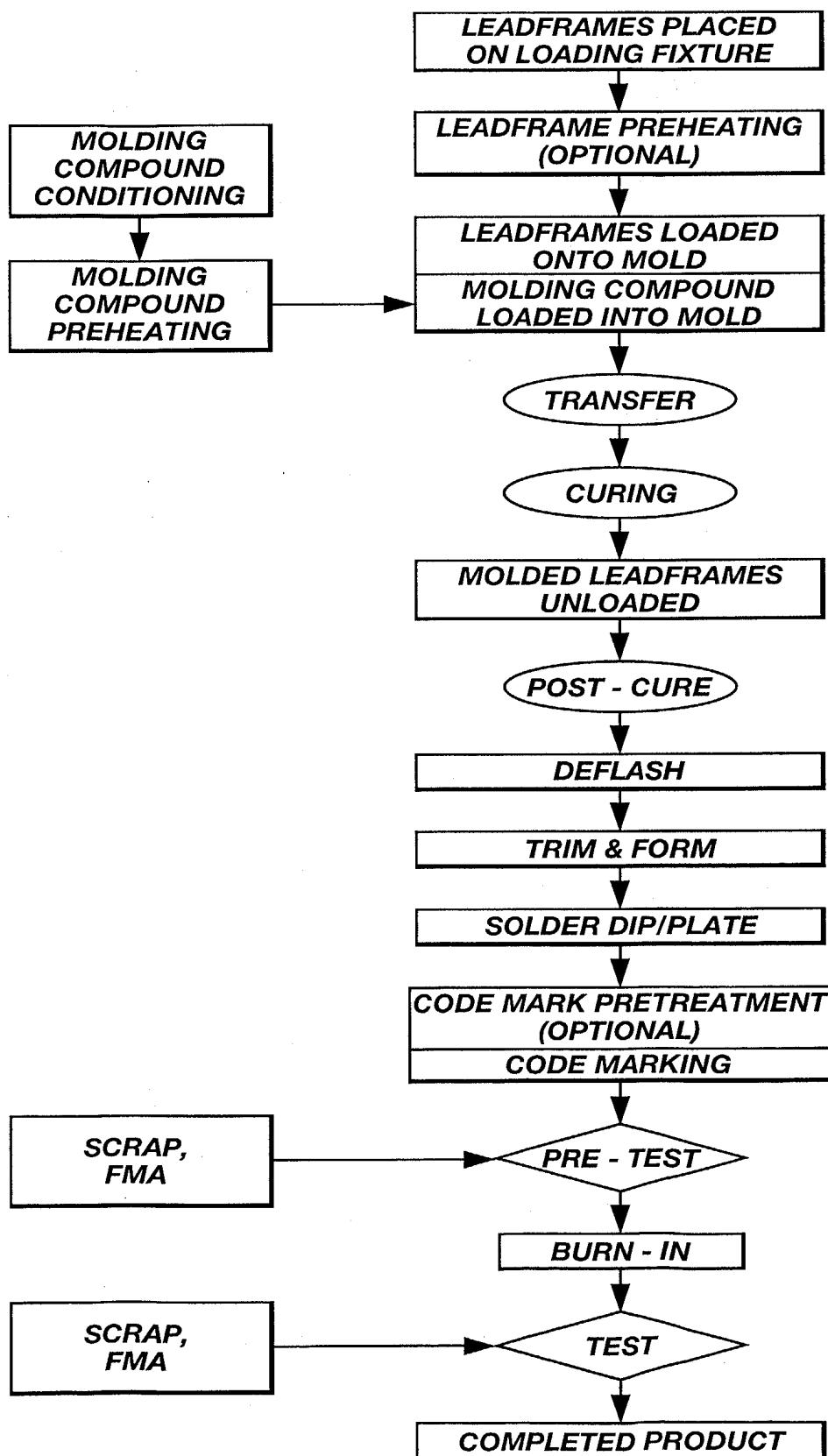
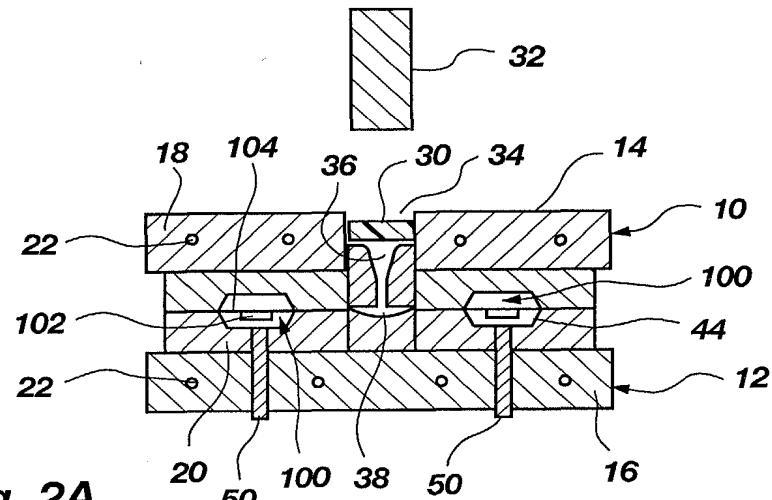


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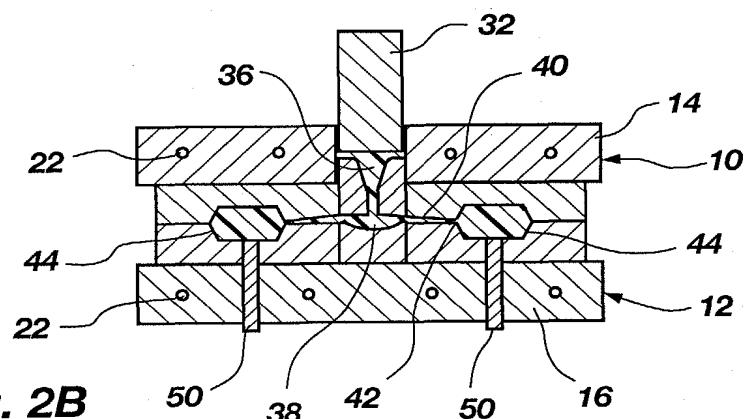


**Fig. 1**  
(PRIOR ART)

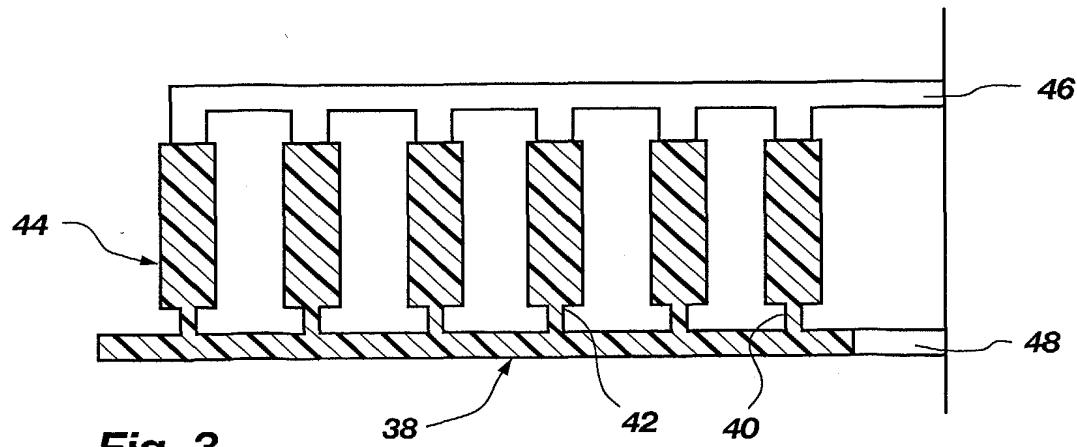
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**Fig. 2A**  
(PRIOR ART)

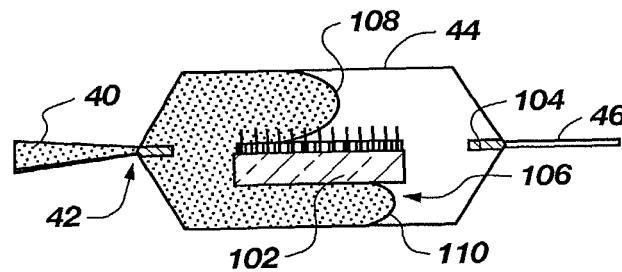


**Fig. 2B**  
(PRIOR ART)

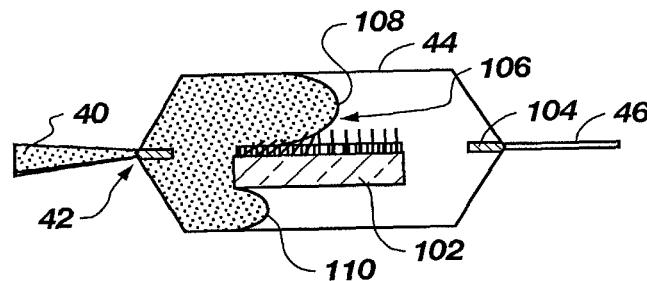


**Fig. 3**  
(PRIOR ART)

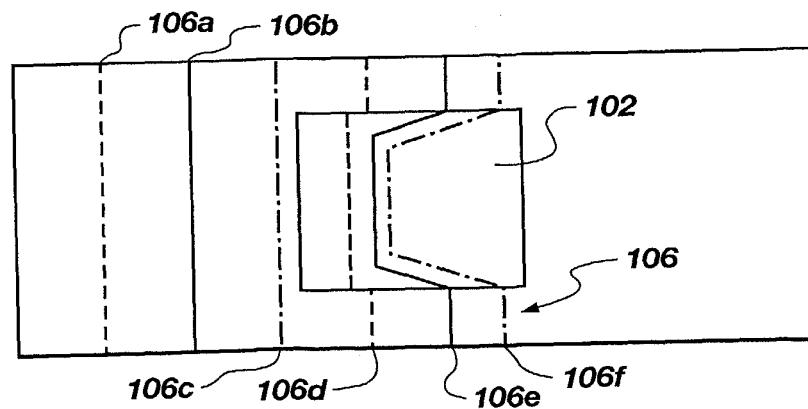
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**Fig. 4A**  
(PRIOR ART)



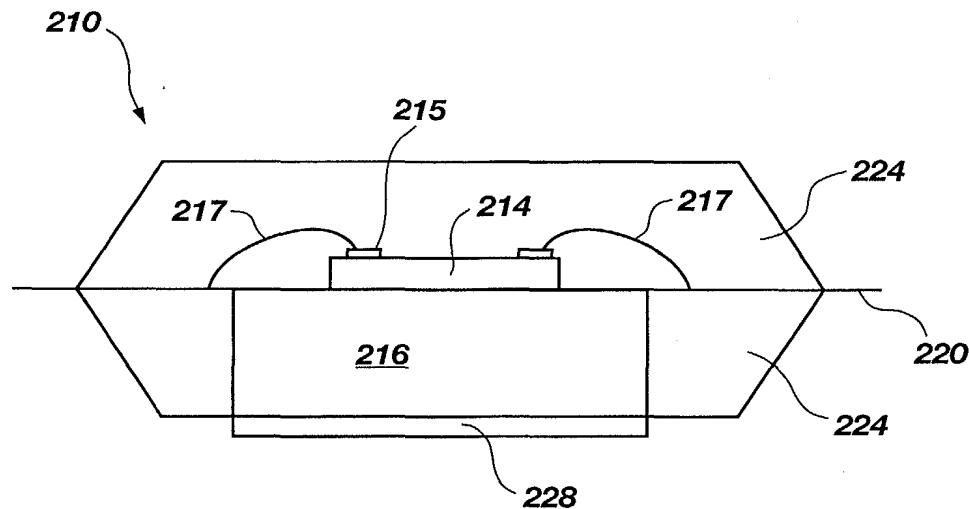
**Fig. 4B**  
(PRIOR ART)



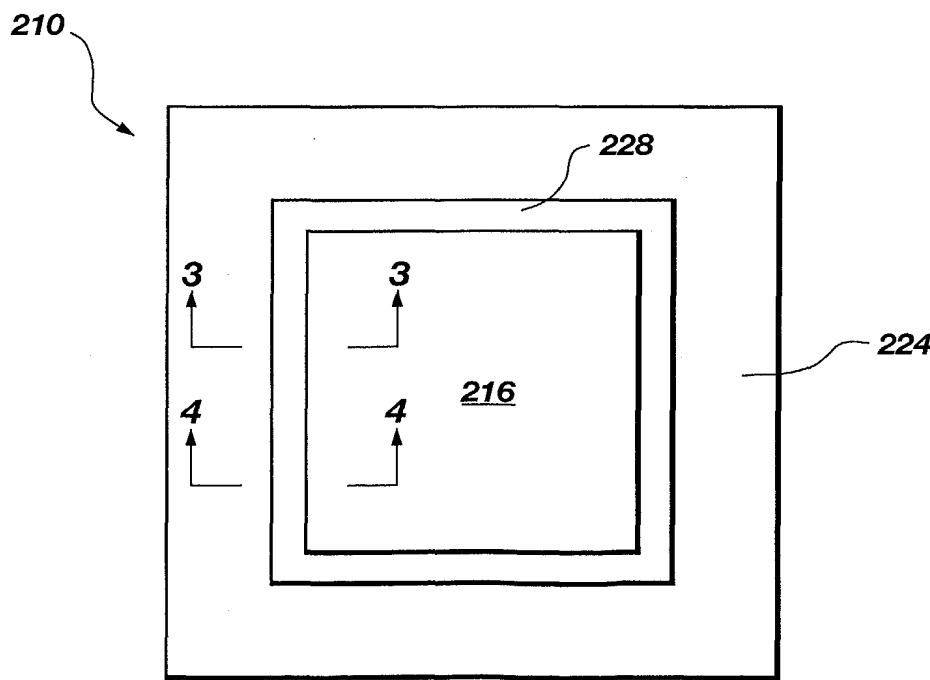
**Fig. 4C**  
(PRIOR ART)

TITLE: METHOD AND APPARATUS FOR TRANSFER  
MOLDING ENCAPSULATION OF A SEMICONDUCTOR...  
Inventor: Richard W. Wensel  
Docket No.: 3061.6US

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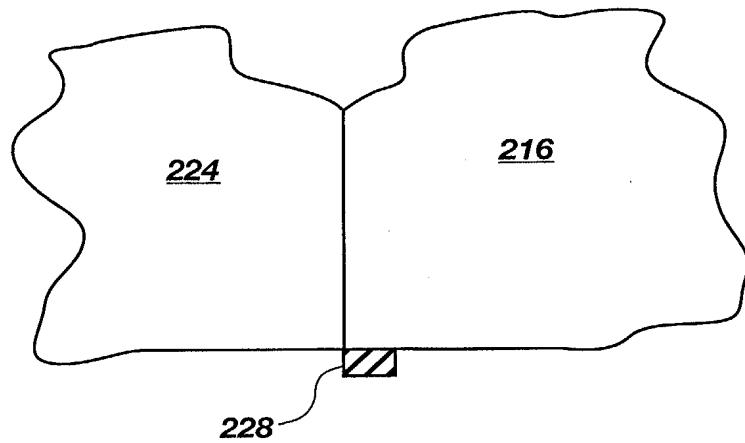


*Fig. 5*

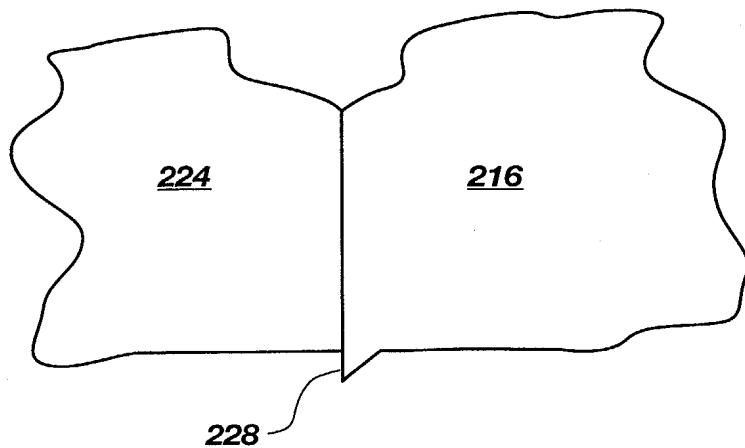


*Fig. 6*

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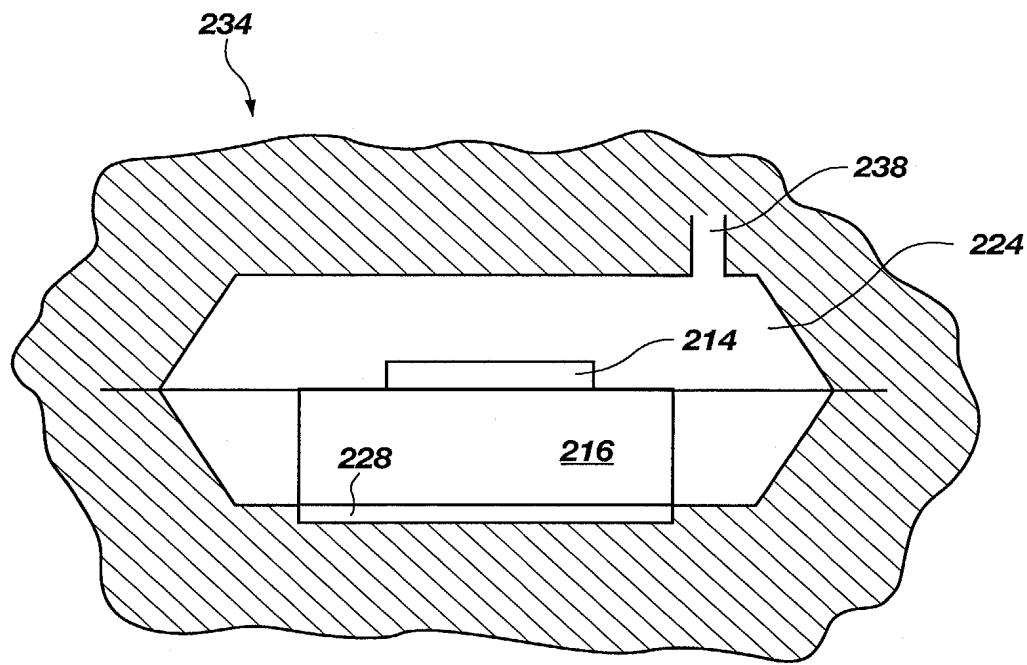


*Fig. 7*



*Fig. 8*

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*Fig. 9*